

ABSTRACT OF THE DISCLOSURE

[0023] A power semiconductor module has a base plate comprising a framewise housing, a cap, and at least one electrically insulated substrate disposed inside the housing. The substrate comprises an insulation body with a plurality of metal connection tracks located thereon and insulated from one another, power semiconductor components located on the connection tracks, and terminal elements leading to the outside of the power semiconductor module for load and auxiliary contacts. Some of these terminal elements in the interior of the power semiconductor module comprise contact springs, which are disposed between the connection tracks and contact points on a printed circuit board. The printed circuit board has conductor tracks, which connect the contact points to contact elements that lead to the outside of the power semiconductor module.